

EAST Search History**EAST Search History (Prior Art)**

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	403	257/791.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2010/05/13 14:00
L2	10601	438/124.ccls. 438/126.ccls. 438/127.ccls. 257/787.ccls. 257/788.ccls. 257/791.ccls. 257/e23.12.ccls. 257/ e21.504.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2010/05/13 14:07
L3	433	L2 and ((siloxane polysiloxane organosiloxane organopolysiloxane silicone) same (inject\$6 mold\$6 cavity) same (heat \$6 curable curing cure cured liquid))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2010/05/13 14:07
L4	129	(CHENG-TAMMY DOBRZELEWSKI DOBRZELEWSKI-M DOBRZELEWSKI-MARK SOLOMON-DANIEL SOLOMON-DANIEL-M SOLOMON-DANIEL- STEVEN SOLOMON-D WINDIATE-C WINDIATE- CHRISTOPHER WINDIATE). in.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2010/05/13 14:40
L5	7	L4 and (siloxane polysiloxane organosiloxane organopolysiloxane silicone)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2010/05/13 14:40
L6	276	((siloxane polysiloxane organosiloxane organopolysiloxane silicone) with (composition liquid encapsula\$6 resin epoxy)) and (inject\$6 with (mold\$6 cavity)) and (heat \$6 curable curing cure cured) and (clamp\$6 force ton pressure speed mpa pascal megapascal)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/05/13 14:41

L7	374	((siloxane polysiloxane organosiloxane organopolysiloxane silicone) with (composition liquid encapsula\$6 resin epoxy)) same (inject\$6 with (mold\$6 cavity)) same (heat\$6 curable curing cure cured) same (clamp\$6 force ton pressure speed mpa pascal megapascal)	US-PGPUB; USPAT	OR	ON	2010/05/13 14:43
L8	350	((siloxane polysiloxane organosiloxane organopolysiloxane silicone) with (composition liquid encapsula\$6 resin epoxy)) same (inject\$6 with (mold\$6 cavity)) same (heat\$6 curable curing cure cured) same (addition reaction)	US-PGPUB; USPAT	OR	ON	2010/05/13 15:05
L9	198	((siloxane polysiloxane organosiloxane organopolysiloxane silicone) with (composition liquid encapsula\$6 resin epoxy) with (addition reaction)) same (inject\$6 with (mold\$6 cavity)) same (heat\$6 curable curing cure cured)	US-PGPUB; USPAT	OR	ON	2010/05/13 15:06
L10	38	((siloxane polysiloxane organosiloxane organopolysiloxane silicone) with (composition liquid encapsula\$6 resin epoxy)) same (inject\$6 with (mold\$6 cavity)) same (heat\$6 curable curing cure cured) same (addition near2 reaction)	US-PGPUB; USPAT	OR	ON	2010/05/13 15:11

L11	35	((siloxane polysiloxane organosiloxane organopolysiloxane silicone) with (composition liquid encapsula\$6 resin epoxy)) same (inject\$6 with (mold\$6 cavity)) same (heat\$6 curable curing cure cured) same ((chip die component element ic integrated substrate dice) with (bond \$6 join\$6 attach\$6 mount \$6) with (siloxane polysiloxane organosiloxane organopolysiloxane silicone) with (composition adhe\$8))	US-PGPUB; USPAT	OR	ON	2010/05/13 15:21
L12	68	((siloxane polysiloxane organosiloxane organopolysiloxane silicone) with (composition liquid encapsula\$6 resin epoxy)) same (inject\$6 with (mold\$6 cavity) with gate) same (heat\$6 curable curing cure cured)	US-PGPUB; USPAT	OR	ON	2010/05/13 16:03

EAST Search History (Interference)

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5/ 13/ 10 4:38:51 PM**C:\ Documents and Settings\ ssmoot\ My Documents\ EAST\ Workspaces\ 10565916.wsp**